

Intel® SSD 520 Series
(180GB, 2.5in SATA 6Gb/s, 25nm, MLC)

Specifications

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Specifications

Essentials	
Capacity	180 GB
Status	End of Life
Launch Date	Q1'12
Lithography Type	25 nm
Recommended Customer Price	N/A
Performance	
Sequential Read (up to)	550 MB/s
Sequential Write (up to)	520 MB/s
Random Read (8GB Span) (up to)	50000 IOPS
Random Write (8GB Span) (up to)	60000 IOPS
Latency - Read	80 μs
Latency - Write	85 μs
Power - Active	850 mW (MobileMark 2007 Workload)
Power - Idle	600 mW (DIPM)
Reliability	
Vibration - Operating	2.17 G _{RMS} (5-700 Hz)
Vibration - Non-Operating	3.13 G _{RMS} (5-800 Hz)
Shock (Operating and Non-Operating)	1,500 G/.5 msec
Operating Temperature Range	0°C to 70°C
Mean Time Between Failures (MTBF)	1,200,000 Hours
Uncorrectable Bit Error Rate (UBER)	1 sector per 10 ¹⁶
Warranty Period	5 yrs
Package Specifications	
Components	Intel NAND Flash Memory Multi-Level Cell (MLC) Technology
Weight	Up to 78 grams
Form Factor	2.5" 7mm
Interface	SATA 3.0 6Gb/S
Advanced Technologies	
Enhanced Power Loss Data Protection	No
Hardware Encryption	AES 128 bit

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Intel® SSD 520 Series

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PCN/MDDS Information

922663: [PCN](#)

923333: [PCN](#) | [MDDS](#)

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

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